SF315C 阻燃型黑色聚酰亚胺薄膜覆盖膜

SF315C Flame-resistant type black polyimide film based coverlay

特点

- 透明度低, 遮光性佳。
- 粘结强度高, 尺寸稳定性好。
- 阻燃性达到UL94 V-0级。
- 优秀的耐热性、耐化学性和电性能。
- 溢胶量低,加工性好,适于快速压合和传统压合。
- 满足RoHS指令要求,不含铅、汞、镉、六价铬、 多溴联苯、多溴联苯醚等。

FEATURES

- Low transparence, excellent light-blocking.
- High bonding strength, good dimensional stability,
- Flammability UL94 V-0.
- Excellent soldering reliability, chemical resistance and electrical properties.
- Low adhesive flowing, good processability, suitable for both fast and traditional lamination style.
- Compatible with EU RoHS directive, free of Pb,Hg, Cd, Cr⁶⁺, PBB, PBDE, etc..

应用领域

挠性印制电路板用覆盖膜。

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APPLICATIONS

Coverlay for FPC.

性能表 GENERAL PROPERTIES

| 性能项目 Test Item | | 试验处理条件 | 单位 Unit | 性能数据 Property Data | | |
|---|----|------------------------|------------|----------------------|-------------------|-----------------|
| | | Treatment Condition | | IPC 标准值 [*] | 典型值 Typical Value | |
| | | | | Standard | SF315C 0305 | SF315C 0309 |
| 溢胶量 | | A | mm | | <0.15 | <0.15 |
| Resin Flow | | | | - | < 0.15 | <0.15 |
| 剥离强度1 | | А | N/m | ≥0.7 | 0.71 | 0.83 |
| Peel Strength (90°) ¹ | | 288℃,5s | m | ≥0.53 | 0.70 | 0.77 |
| 热应力 ¹ Thermal Stress ¹ | | 288℃,20s | - | - | 无分层、无起泡 | 无分层、无起泡 |
| | | | | | No delamination | No delamination |
| 尺寸稳定性 | MD | 撕纸后 | | | ±0.15 | ±0.15 |
| Dimensional | TD | After peeling | % | ±0.2 | 1045 | 10.45 |
| Stability | 1D | off the paper | | | ±0.15 | ±0.15 |
| 耐化学性(剥离强度保持 | | After Chemical | | | | |
| 率) | | Exposure | % | ≥80 | >85 | >85 |
| Chemical Resistance | | 暴露化学品后 | | | | |
| 燃烧性 Flammability | | C-48/23/50 | - | UL94 V-0 | UL94 V-0 | UL94 V-0 |

注释 Explanations: C = Humidity conditioning; E = 恒温处理条件 Temperature conditioning.

1. 与铜箔光面压合再固化后测试。Testing after laminating with shining side of copper foil in suitable condition.

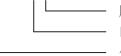
* Certified to IPC-4203/2 Epoxy adhesive on one or two sides of poyimide dielectric

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产品规格代码描述 Product Code Description

SF315C 10 25



胶粘剂厚度 Adhesive Thickness: 13 - 13µ m; 25 - 25µ m

PI 膜厚度 PI film Thickness: 10 - 25µ m

生益覆盖膜产品编号 Shengyi Coverlay Designation

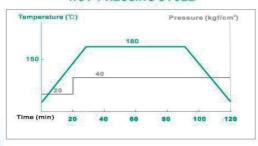
<u>常规产品表 SPECIFICATIONS OF STANDARD PRODUCTS</u>

| 产品规格 | PI 膜厚度(µ m) | 胶粘剂厚度(µm) | |
|----------------|-------------------------|--------------------------|--|
| Specifications | PI film Thickness (μ m) | Adhesive Thickness (µ m) | |
| SF315C 0515 | 12.5 | 15 | |
| SF315C 1025 | 25 | 25 | |

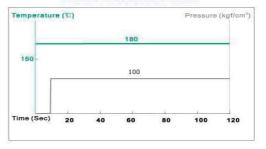
<u>新规格产品表 SPECIFICATIONS OF NEW MODELS</u>

| 产品规格 | PI 膜厚度(µm) | 胶粘剂厚度(µm) | 应用领域 | |
|----------------|------------------------------|--------------------------|----------------------|--|
| Specifications | PI film Thickness (μ m) | Adhesive Thickness(µ m) | Applications | |
| SF315C 0515 | 12.5 | 15 | 手机天线 | |
| SF315C 1025 | 25 | 25 | Mobile phone antenna | |
| SF315C 0305 | 7.5 | 5 | 无线充电 | |
| SF315C 0309 | 7.5 | 9 | 一 | |
| SF315C 0409 | 10 | 9 | | |

压板推荐 PRESS PROPOSE HOT PRESSING CYCLE



FAST PRESSING CYCLE



传压参数根据不同设备及产品规格需作相应调整;采用快压方式,后固化条件是 155-165℃、60-90 分钟。 The parameters of hot Pressure need to be adjusted according to different equipment and product specifications. After fast press, the curing condition is 150-160℃ for 60-90min.

包装 PURCHASING INFORMATION

产品宽度250+2/-0mm或500+2/-0mm,每卷100+2/-0米或200+2/-0米;其它规格、尺寸可根据客户要求而定。 SF315C is supplied in rolls and standard width of 250+2/-0mm or 500+2/-0mm. Roll length is 100+2/-0m or 200+2/-0m. Other sizes could be available upon request.

储存条件 STORAGE CONDITION

贮存在干燥的室内;以原始包装贮存在4-10 ℃的冷藏室里,贮存期为三个月。 Stored in the room of dryness. Three months when stored in the original packaging at 4-10 ℃. \mathbb{Z}